

PCN#: [EPPO2-EX-25-0017]

Product Change Notice (PCN)

Subject: Assembly & sorting factory addition for RL78/F23 and F24 series and HWQFN products

Publication Date: 3/21/2025 Effective Date: 8/29/2025

Revision Description: Initial Release

Description of Change:

Assembly & sorting factory addition for RL78/F23, F24 series, and 32pin HWQFN products.

Additional factory: Renesas Semiconductor KL Sdn. Bhd. (RSKL) Existing assembly factory: Greatek Electronics Inc. (Greatek) Existing Sorting factory: King Yuan Electronics Co., Ltd. (KYEC) The following materials are also changed. See below for details.

[Details of change]

No	ltem	Additional factory		Existing	; factory
		H'	WQFN with Half-	cut Wettable flar	nk
1	Assembly / Sorting factory	Assembly	Sorting	Assembly	Sorting
		RSKL	RSKL	Greatek	KYEC
2	Bonding wire material	Cu, φ23um		Cu, φ20um	
3	Lead frame	Common lead frame		individual lead frame	
4	Die attach material	Equivalent material (Ag paste)			
5	Mold resin material	Equivalent material (Resin for Cu wire)			re)
6	Marking specification	There are differences (Refer to the Marking)			rking)
7	Package outline	There are differences (Refer to the Package outline)			(e outline)
8	Packing	Factory standard Tape/Reel A Base Standard Tape		d Tape/Reel B	
9	Storage conditions. after opening	30°C/70%RH/ within 168hr 30°C/60%RH/ with			/ within 168hr

Affected Product List:

Refer to "Product List" in "Appendix".

Reason for Change:

For stable supply of products

Impact on Fit, Form, Function, Quality & Reliability:

The change will have no impact on the fitness, function, quality and reliability of the devices.

Package Outline: Please refer to the "Appendix".

Product Identification:

There is no change in Part number.

Our production history data can be queried by using the trace code of the product.

Qualification Status:

4/10/2025 It will be available to provide.

Sample Availability Date:

7/18/2025 (Deadline for sample request 6/6/2025)

Device Material Declaration:

Available upon request.



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Note:

- 1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the changes as approved.
- If timely acknowledgement is provided by customers, then customers shall have 90 days from the date of receipt of this PCN to make any objections to this PCN. If customers fail to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.
- 3. If customer cannot accept the PCN then customers must provide Renesas with the last order quantity and purchase order.

For additional information regarding this notice, please contact your Renesas sales representative.

Appendix 1

■Part number specification

There is no change in Part number.

■Marking specification

Marking specifications will be changed as follows.

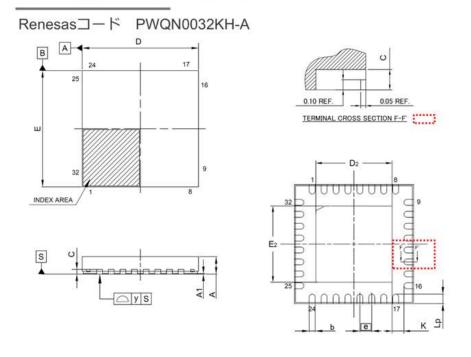


■Explanation of changes

No	Material change	Explanation of changes		
2	Bonding wire material	It is a proven material for automotive Cu wire products.		
3	Lead frame	It is a proven material for automotive Cu wire products.		
4	Die attach material	It is a proven material for automotive Cu wire products.		
5	Mold resin materia	It is a proven material for automotive Cu wire products.		

New

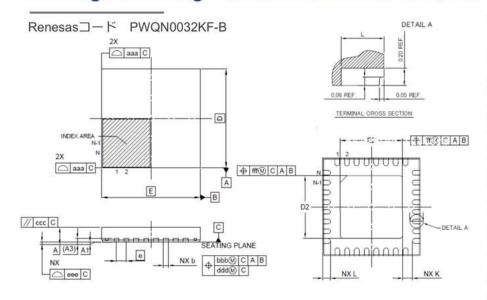
Package Drawing (Renesas Semiconductor KL Sdn.Bhd.)



Reference	Dimen	sion in Mill	imeters	
Symbol	Min.	Nom.	Max.	
D	4.85	5.00	5.15	
Е	4.85	5.00	5.15	
Α	-	_	0.80	
A ₁	0.00	_	0.05	
b	0.18	0.25	0.30	
е	0.50 BSC			
Lp	0.35	0.40	0.45	
у		-	0.08	
С	_	0.20	8-0	
К	0.20	-	-	
D ₂	_	3.20	1-	
E ₂		3.20	_	

Existing factory

Package Drawing (Greatek Electronics Inc.)



Reference	Dimen	sion in Mill	imeters
Symbol	Min.	Nom.	Max.
A	-	-	0.80
A1	0.00	-	0.05
A3	- "	0.20 REF.	
b	0.18	0.25	0.30
D	-	5.00	-
E		5.00	-
е	-	0.50	-
N	32		i e
L	0.35	0.40	0.45
K	0.20	-	-
D2	3.15	3.20	3.25
E2	3.15	3.20	3.25
ааа	177	-	0.15
bbb	-	-	0.10
ccc	=	-	0.10
ddd	-	_	0.05
eee	-	-	0.08
fff	-	-	0.10

Package Drawing (Dimension comparison)

RSKL package symbols complied to JEITA standard, and Greatek package symbols complied to JEDEC standard.

RSKL SymbolはJEITA基準に準拠 Greatek SymbolはJEDEC規格に準拠しています。

RSKL Symbol	5x5mm 32pin HWQFN PWQN0032KH-A Dimension in Millimeters		Greatek Symbol	5x5mm 32pin HWQFN PWQN0032KF-B Dimension in Millimeters			
A	-	(*)	0.80	A	0.40		0.80
A1	0.00	0.40	0.05	A1	0.00	2.43	0.05
С	-	0.20	-	A3		0.20 REF	
b	0.18	0.25	0.30	b	0.18	0.25	0.30
D	4.85	5.00	5.15	D	-	5.00	2
Е	4.85	5,00	5.15	E		5.00	
е		0.50 BSC		е	1.0	0.50	- 50
-	-	275		N		32	
Lp	0.35	0.40	0.45	L	0.35	0.40	0.45
				К	0.20		20
D2	-	3.20	- 2	D2	3.15	3.20	3.25
E2	-	3.20	-	E2	3.15	3.20	3,25
	-	-	- 6	aaa		-	0.15
	- 5	181	- 51	bbb			0.10
-	-	15	5.	ccc		3.0	0.10
-	-	(#)	+1	ddd	0.00	0.00	0.05
у	-	-	0.08	eee	-		0.08
	-	593	-	fff			0.10

■Packing change (1/2)

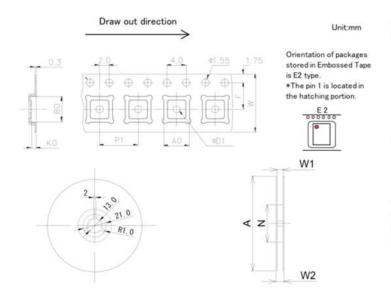
There are no changes to the tray.

Tape & Reel will be changed as follows.

Additional factory

Packing Specification Tape & Reel Outline Drawing

(Renesas Semiconductor KL Sdn.Bhd.)

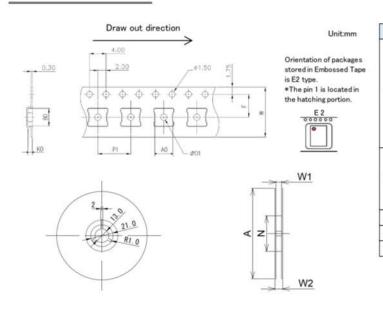


Tape Code		E12*08-B8CA
9*	W	12.0
	P1	8.0
	AO	5.3
Tape Dimensions (mm)	B0	5.3
	KO	1.0
	F	5.5
	D1	1.5
	Α	330
D 10:	N	100
Reel Dimensions (mm)	W1	13.5
	W2	17.5
Maximum storage Pcs. IC/ Reel		2500
Material		Carbon PS
Surface resistance		1.0x10 [^] 4≦R<1.0x10 [^] 11Ω

Existing factory

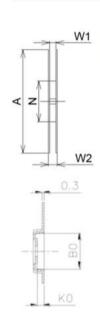
Packing Specification Tape & Reel Outline Drawing

(Greatek Electronics Inc.)



Tape Code	ECPKG0505-151	
	W	12.0
	P1	8.0
	A0	5.3
Tape Dimensions (mm)	B0	5.3
	K0	1.1
	F	5.5
	D1	1.6
	Α	330
D D' /)	P1 A0 B0 K0 F D1 A N W1 W2 Reel	102
Reel Dimensions (mm)		12.8
		18.4
Maximum storage Pcs. IC/ Reel		2500
Material		Carbon PS
Surface resistance		1.0x10 ² 4≦R<1.0x10 ¹¹ Ω

Packing Specification Tape & Reel Outline Drawing (Dimension comparison)



Tape Code		E12*08-B8CA
	W	12.0
	P1	8.0
	AO	5.3
Tape Dimensions (mm)	BO	5.3
	K0	1.0
	F	5.5
	D1	1.5
	Α	330
D. (D)	N	100
Reel Dimensions (mm)	W1	13.5
	W2	17.5
Maximum storage Pcs. IC/	Reel	2500
Material		Carbon PS
Surface resistance		1.0x10^4≤R<1.0x10^11Ω

追加拠点仕様

	_	
Tape Code		ECPKG0505-151
	W	12.0
	P1	8.0
	A0	5.3
Tape Dimensions (mm)	B0	5.3
	K0	1.1
	F	5.5
	D1	1.6
	Α	330
D (D)	N	102
Reel Dimensions (mm)	W1	12.8
	W2	18.4
Maximum storage Pcs. IC/	Reel	2500
Material		Carbon PS
Surface resistance		1.0x10 ⁴ ≤R<1.0x10 ¹ 11Ω

■4M changing points

Item	Check Result	Judgement
Machine	For bonding Cu wire products, we use the same level of equipment as in our existing factory. The additional plant was also equipped with an atmosphere that is resistant to oxidation as a countermeasure against the involvement of Cu wires. In addition, we have a track record of Cu wi application products in similar products, and we have confirmed that there are no problems when starting the construction of this product.	
Method	They are joined by the same bonding method as Au wire products.	O No risk
Man	Authorized workers at the plant will be engaged.	
Material	Only approved Cu wire materials are used. We apply certified materials that correspond to Cu wire products. In addition, we have also conducted reliability tests on finished products equivalent to those of current products (Au wire products) to confirm that there are no problems.	O No risk

Appendix 2 Product List

RL78/F23 series:

Product P/N	Packing
R7F123FBG3ANP-C#AAO	Bulk (Tray)
R7F123FBG4ANP-C#AAO	Bulk (Tray)
R7F123FBG3ANP-C#BAO	Full Carton (Tray)
R7F123FBG4ANP-C#BAO	Full Carton (Tray)
R7F123FBG3ANP-C#BAQ	Full Carton (Tray)
R7F123FBG4ANP-C#BAQ	Full Carton (Tray)
R7F123FBG3ANP-C#HAO	Tape&Reel
R7F123FBG4ANP-C#HAO	Tape&Reel
R7F123FBG3ANP-C#HAQ	Tape&Reel
R7F123FBG4ANP-C#HAQ	Tape&Reel

RL78/F24 series:

Product P/N	Packing
R7F124FBJ3ANP-C#AAO	Bulk (Tray)
R7F124FBJ4ANP-C#AAO	Bulk (Tray)
R7F124FBJ3ANP-C#BAO	Full Carton (Tray)
R7F124FBJ4ANP-C#BAO	Full Carton (Tray)
R7F124FBJ3ANP-C#BAQ	Full Carton (Tray)
R7F124FBJ4ANP-C#BAQ	Full Carton (Tray)
R7F124FBJ3ANP-C#HAO	Tape&Reel
R7F124FBJ4ANP-C#HAO	Tape&Reel
R7F124FBJ3ANP-C#HAQ	Tape&Reel
R7F124FBJ4ANP-C#HAQ	Tape&Reel